



Press Release

Unisem and FlipChip International Sign Licensing Agreement For Wafer Bumping and Wafer Level Packaging Technologies

Partnership with UAT Allows FCI to Extend Its Reach to the Asian Market

Kuala Lumpur, Malaysia – June 16, 2008 – Unisem (M) Berhad (Unisem) and its subsidiary Unisem-Advanpack Technologies Sdn Bhd (UAT) announced today that they have entered into an agreement with FlipChip International, LLC (FCI) for the licensing of FCI's wafer bumping and wafer level packaging technologies. As part of the agreement, UAT will license FCI's core technologies, including its premier Spheron™ technology. FCI will further solidify its investment in the partnership by becoming a shareholder of UAT.

FCI's wafer bumping technology offers complete bumping solutions for fine pitch devices, including 0.125mm pitch densities and high-reliability applications requiring JEDEC Level 1 capability with the smallest form factor available. FCI's Spheron™ technology is designed for high-frequency RF wafer level chip scale packaging and utilizes a new dielectric material, which offers improved electrical and mechanical performance in handheld advanced mobile devices and other demanding applications.

"This agreement comes at an ideal time, as the global demand for flip chip and wafer level packaging continues to grow significantly in market share due to the substantial cost savings, device size reduction and increased performance benefits," said Bob Forcier, president and CEO of FlipChip International. "Entering into this licensing agreement with Unisem will not only provide benefits for both of our companies, it will make FCI's wafer level technologies available to a host of new customers,"

"This new partnership with FCI will enable Unisem to offer additional cutting-edge wafer bumping and wafer level packaging alternatives to our customers," said S.C. Lau, general manager of UAT. "FCI is providing all necessary documentation, training and engineering support for a fast ramp-up of its wafer bumping and wafer level packaging technologies, which will be quickly integrated into our existing full production environment."



About FCI

FlipChip International, LLC is the leading provider of merchant Wafer Level Packaging and flip chip bumping to the semiconductor market through its Phoenix, Arizona facility and its global licensees. Flip Chip International, LLC is a privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a subsidiary of RoseStreet Labs LLC, a supplier of products and services for the semiconductor services, renewable energy markets and life sciences. For more information about FlipChip International, LLC, visit www.flipchip.com.

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about Unisem, please visit www.unisemgroup.com.